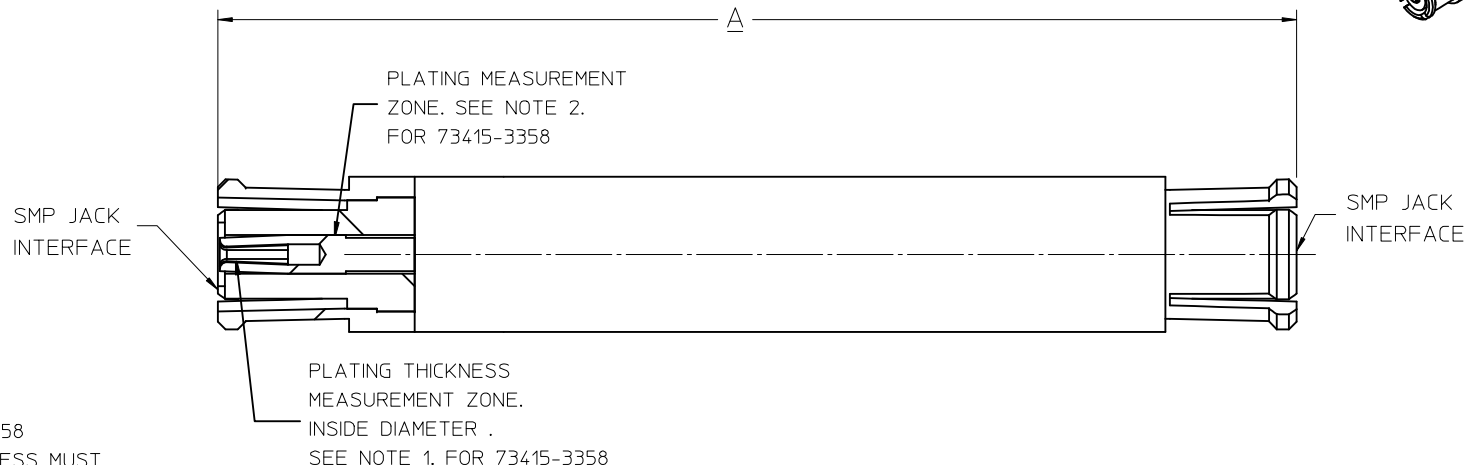
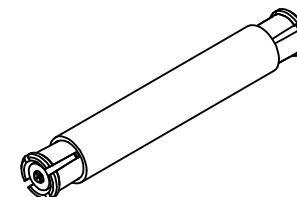


MATERIALS AND FINISHES:

BODY BERYLLIUM COPPER
PLATED GOLD

CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON



NOTE 1: FOR 73415-3358
GOLD PLATING THICKNESS MUST
BE 10 MICROINCHES MINIMUM AT
STATED LOCATION.

NOTE 2: FOR 73415-3358
GOLD PLATING THICKNESS MUST
BE 30 MICROINCHES MINIMUM AT
STATED LOCATION.

73415-3356	PLACE 73415-3351 INTO SMALL TRAY
73415-3355	PLACE 73415-3350 INTO SMALL TRAY
PART NO.	DESCRIPTION

73415-3359	.646 REF	16.40 REF
73415-3358	.677 REF	17.20 REF
73415-3357	.449 REF	11.40 REF
73415-3354	1.131 REF	28.73 REF
73415-3353	.571 REF	14.50 REF
73415-3352	.520 REF	13.21 REF
73415-3351	.799 REF	20.30 REF
73415-3350	.937 REF	23.80 REF
PART NO.	IN	MM

PS-89675-3320	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 326.1	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: ADDED NOTE 1&
NOTE 2

EC NO: URF2009-0237
2008/11/05
DRW:CLL I
CHKD: 2008/11/11
APPR:MHUANG 2008/11/11

DESCRIPTION

REV: D1

QUALITY SYMBOLS

▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .005	± .0004
3 PLACES	± .005	± .0004
2 PLACES	± .005	± .0004
1 PLACE	± .005	± .0004

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM/IN

DRAWN BY DATE
TEF 2001/05/22

CHECKED BY DATE
SSS 2001/05/22

APPROVED BY DATE
GMH 2001/05/22

MATERIAL NO.
SEE TABLE

SIZE
C

SCALE
DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

TITLE
SMP JACK TO JACK ADAPTER
50 OHMS SMP-J/J/ADP

MOLEX INCORPORATED

DOCUMENT NO.
SD-73415-335

SHEET NO.
1 OF 1

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION